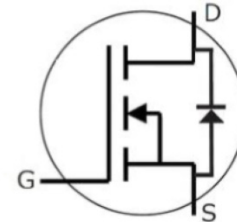
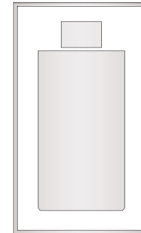


# CPM3-1200-0160A

## WolfSpeed SiC Gen 3 MOSFET

### Description

This is WolfSpeed's 3rd generation of high performance silicon carbide MOSFET in a packageless bare die format to be implemented into any custom module design. The high blocking voltage with low on-resistance, high speed switching with low capacitance make this MOSFET ideal for applications in renewable energy, high voltage DC-DC converter, power supplies and UPS.



G - Gate  
S - Source  
D - Drain

Package Types: Bare Die  
PN: CPM3-1200-0160A

### Features

- Enhanced 3rd Generation SiC MOSFET
- High blocking voltage with low on-resistance
- Easy to parallel and simple to drive
- Resistant to latch-up

### Applications

- HVAC motor drive
- Renewable energy
- High voltage DC-DC converter
- Switch mode power supplies
- UPS

### Absolute Maximum Ratings

Stress beyond those listed under absolute maximum ratings may damage the device.

Parameter	Symbol	Rating	Unit
Drain-Source Voltage, across $T_{vj}$	$V_{DS(max)}$	1200	V
Maximum Gate-Source Voltage, Peak Transient Capability	$V_{GS(max)}$	-8/+19	V
Continuous Drain Current, $V_{GS} = 15V$ , assumes die packaged in TO-247 package with typical $R_{th(j-c)} = 1.29K/W$	$I_D$	$T_c = 25^\circ C$	17
		$T_c = 100^\circ C$	12
Pulsed Drain Current, $t_p$ limited by $T_{vj(max)}$	$I_{D(pulse)}$	34	A
Virtual Junction and Storage Temperature	$T_{Vj}, T_{stg}$	-55 to +150	$^\circ C$
Maximum Processing Temperature, in non-reactive ambient	$T_{proc}$	325	$^\circ C$

### Recommended Operating Conditions

Parameter	Symbol	Rating	Unit
Recommended Operating Gate - Source Voltage	$V_{GS(op)}$	-4/+15	V



### Electrical Characteristics ( $T_{VJ} = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1200			V	$V_{GS} = 0\text{ V}, I_{DS} = 100\ \mu\text{A}$
Gate Threshold Voltage	$V_{GS(th)}$	1.8	2.8	3.6	V	$V_{DS} = V_{GS}, I_{DS} = 2.33\ \text{mA}$
			2.2		V	$V_{DS} = V_{GS}, I_{DS} = 2.33\ \text{mA}, T_{VJ} = 150^\circ\text{C}$
Zero Gate Voltage Drain Current	$I_{DSS}$		1	6	$\mu\text{A}$	$V_{DS} = 1200\text{V}, V_{GS} = 0\ \text{V}$
Gate-Source Leakage Current	$I_{GSS}$		10	17	nA	$V_{GS} = 15\ \text{V}, V_{DS} = 0\ \text{V}$
Drain-Source On-State Resistance	$R_{DS(on)}$	112	160	208	m $\Omega$	$V_{GS} = 15\ \text{V}, I_{DS} = 8.5\ \text{A}$
			256			$V_{GS} = 15\ \text{V}, I_{DS} = 8.5\ \text{A}, T_{VJ} = 150^\circ\text{C}$
Transconductance	$g_{fs}$		5.2		S	$V_{DS} = 20\ \text{V}, I_{DS} = 8.5\ \text{A}$
			4.9			$V_{DS} = 20\ \text{V}, I_{DS} = 8.5\ \text{A}, T_{VJ} = 150^\circ\text{C}$
Input Capacitance	$C_{iss}$		632		pF	$V_{GS} = 0\ \text{V}, V_{DS} = 1000\text{V}$ $f = 1\ \text{MHz}$ $V_{AC} = 25\text{mV}$
Output Capacitance	$C_{oss}$		39			
Reverse Transfer Capacitance	$C_{rss}$		3			
$C_{oss}$ Stored Energy	$E_{oss}$		22.5		$\mu\text{J}$	$V_{DS} = 1200\ \text{V}, f = 1\ \text{MHz}$
Internal Gate Resistance	$R_{G(int)}$		8		$\Omega$	$f = 1\ \text{MHz}, V_{AC} = 25\text{mV}$
Gate to Source Charge	$Q_{gs}$		9		nC	$V_{DS} = 800\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}$ $I_{DS} = 8.5\ \text{A}$
Gate to Drain Charge	$Q_{gd}$		12			
Total Gate Charge	$Q_g$		38			

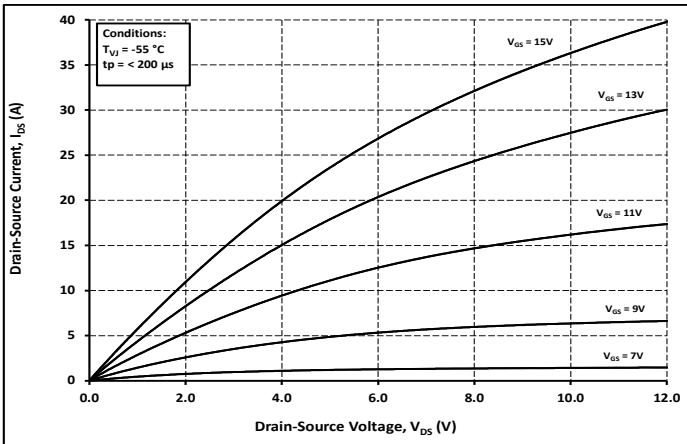
### Reverse Diode Characteristics ( $T_{VJ} = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Typ.	Max.	Unit	Test Conditions
Diode Forward Voltage	$V_{SD}$	4.5		V	$V_{GS} = -4\ \text{V}, I_{SD} = 3\ \text{A}$
		4.0		V	$V_{GS} = -4\ \text{V}, I_{SD} = 3\ \text{A}, T_{VJ} = 150^\circ\text{C}$
Reverse Recovery Time	$t_{rr}$	34		ns	$V_{GS} = -4\ \text{V}, I_{SD} = 8.5\ \text{A}, V_R = 800\ \text{V}$ $dI_f/dt = 844\ \text{A}/\mu\text{s}, T_{VJ} = 150^\circ\text{C}$
Reverse Recovery Charge	$Q_{rr}$	194		nC	
Peak Reverse Recovery Current	$I_{rrm}$	8		A	



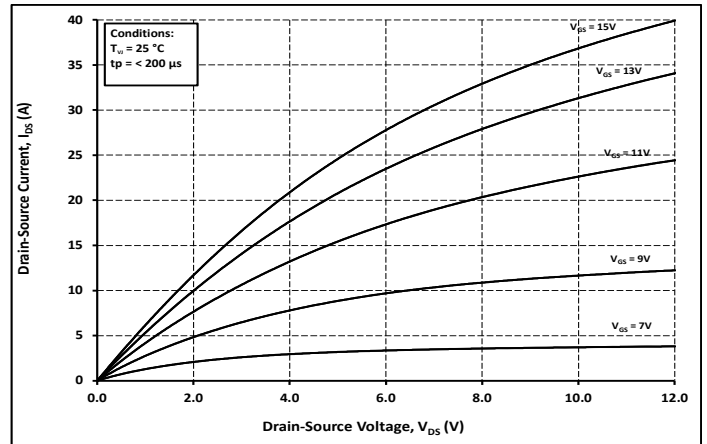
**Typical Performance**

All the graphs are based on a die placed in a TO-247-4L package



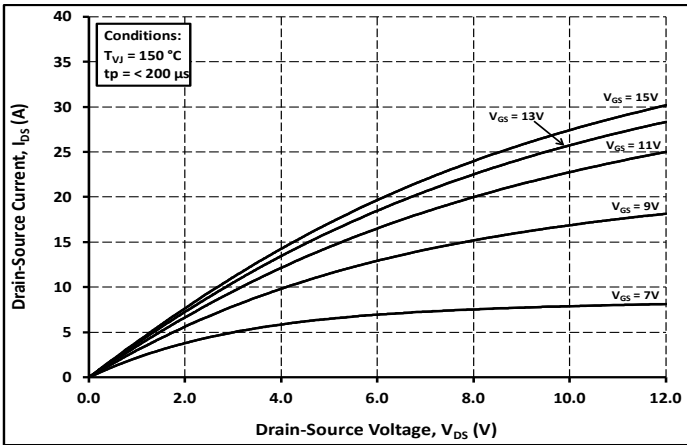
**Figure 1.**

Output Characteristics  $T_{vj} = -55\text{ }^{\circ}\text{C}$



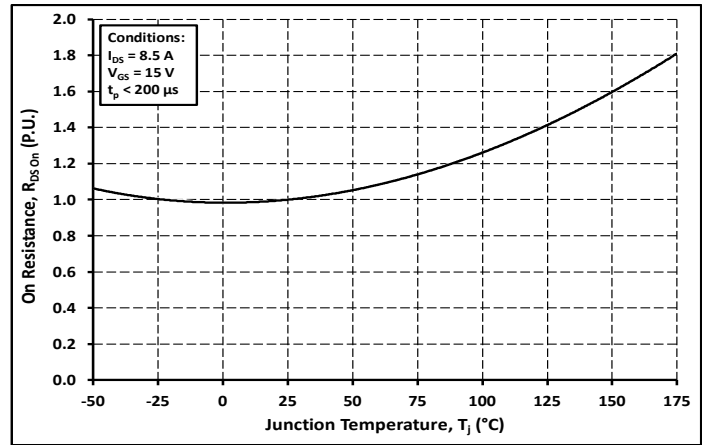
**Figure 2.**

Output Characteristics  $T_{vj} = 25\text{ }^{\circ}\text{C}$



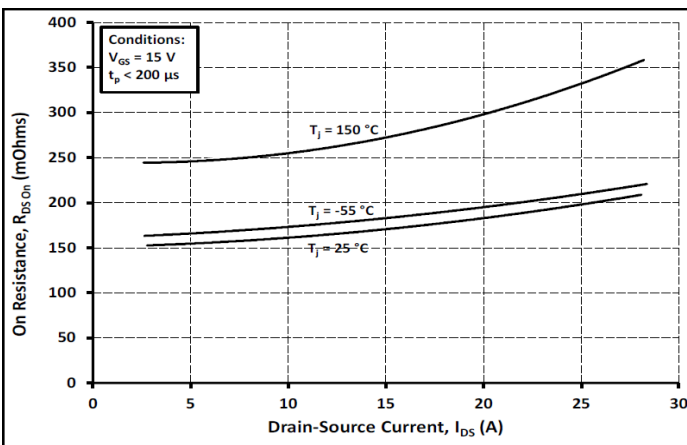
**Figure 3.**

Output Characteristics  $T_{vj} = 150\text{ }^{\circ}\text{C}$



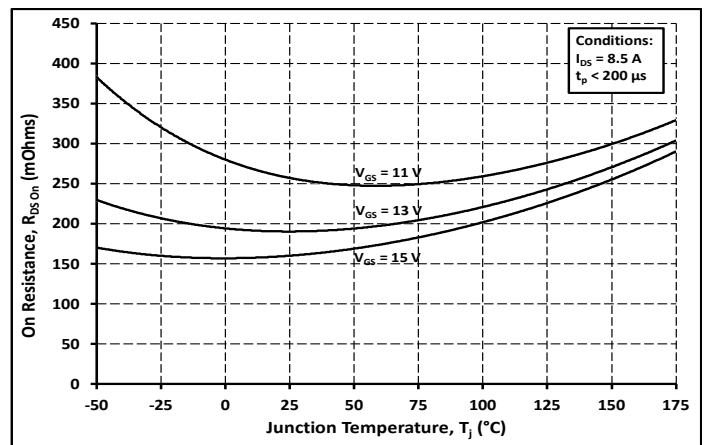
**Figure 4.**

Normalized On-Resistance vs. Temperature



**Figure 5.**

On-Resistance vs. Drain Current For Various Temperatures



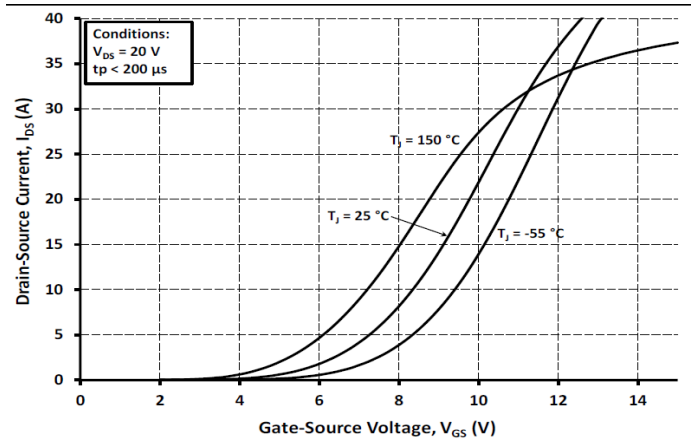
**Figure 6.**

On-Resistance vs. Temperature For Various Gate Voltages



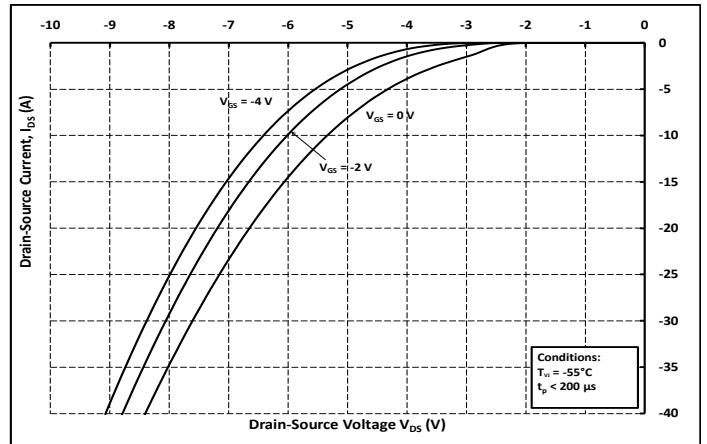
**Typical Performance**

All the graphs are based on a die placed in a TO-247-4L package



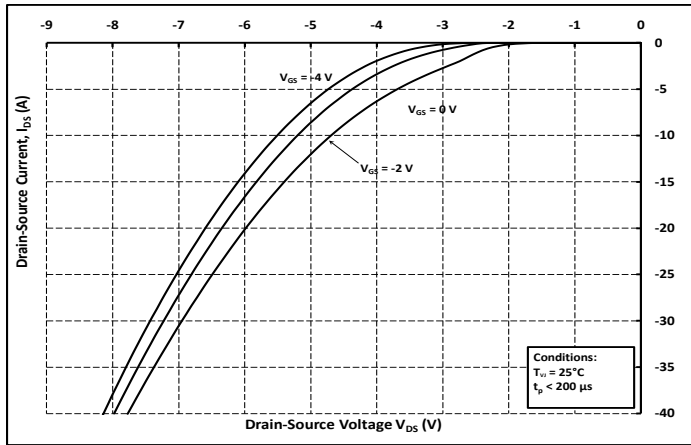
**Figure 7.**

Transfer Characteristic For Various Junction Temperatures



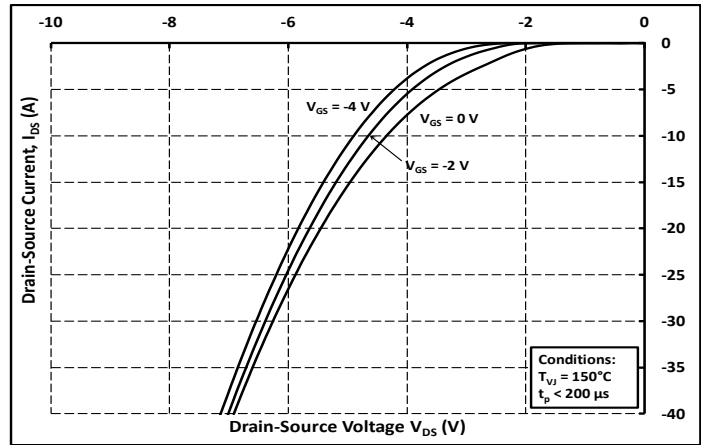
**Figure 8.**

Body Diode Characteristic at  $T_{vj} = -55\text{ °C}$



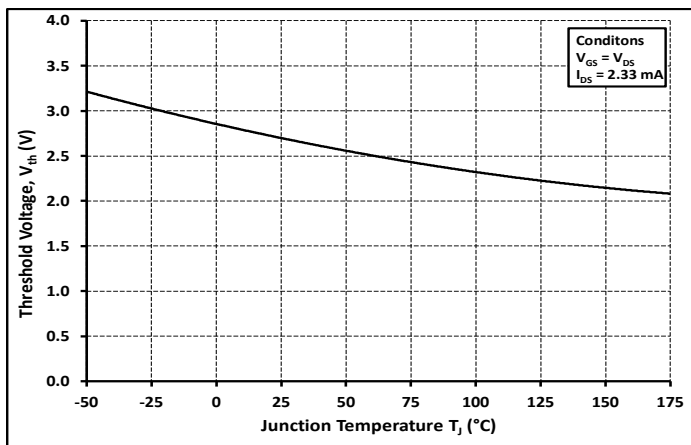
**Figure 9.**

Body Diode Characteristic at  $T_{vj} = 25\text{ °C}$



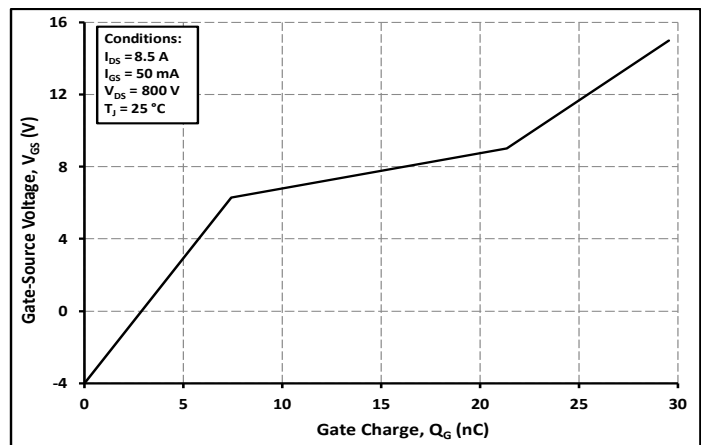
**Figure 10.**

Body Diode Characteristic at  $T_{vj} = 150\text{ °C}$



**Figure 11.**

Threshold Voltage vs. Temperature



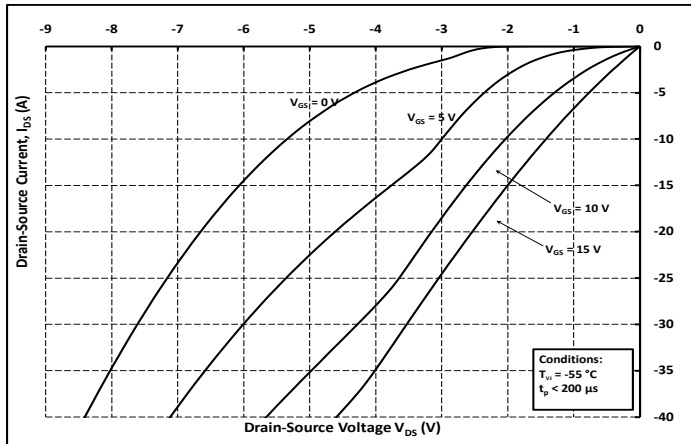
**Figure 12.**

Gate Charge Characteristics



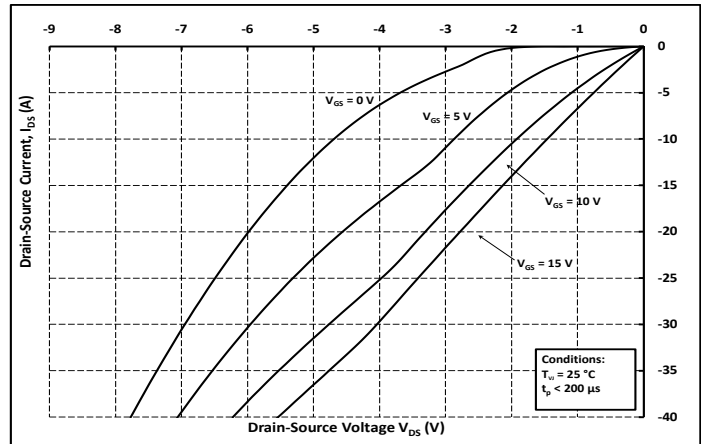
**Typical Performance**

All the graphs are based on a die placed in a TO-247-4L package



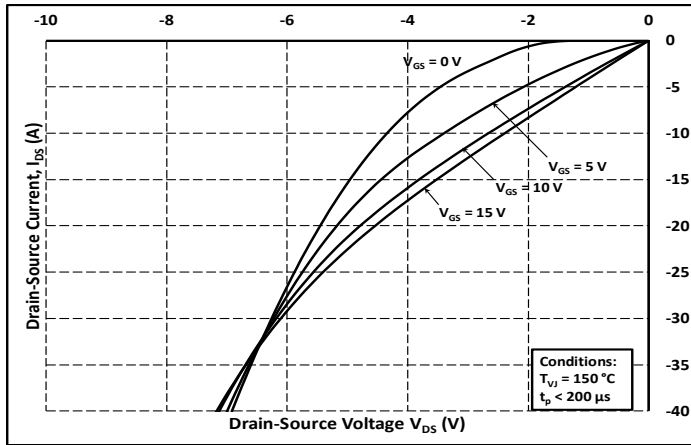
**Figure 13.**

3rd Quadrant Characteristic at  $T_{vj} = -55\text{ °C}$



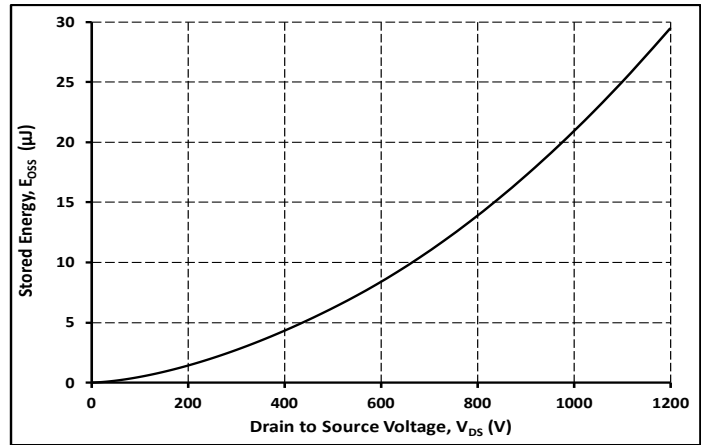
**Figure 14.**

3rd Quadrant Characteristic at  $T_{vj} = 25\text{ °C}$



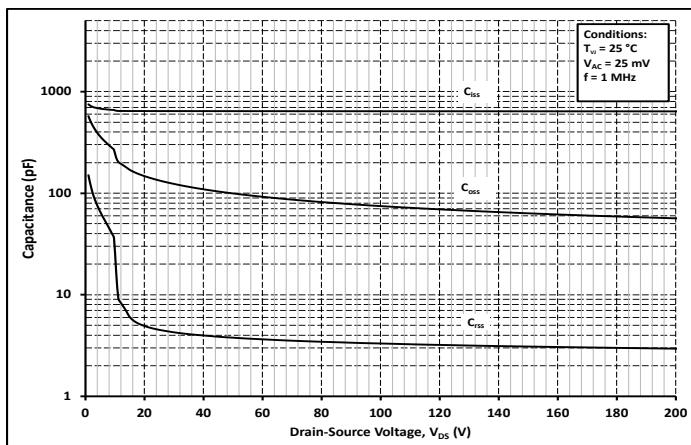
**Figure 15.**

3rd Quadrant Characteristic at  $T_{vj} = 150\text{ °C}$



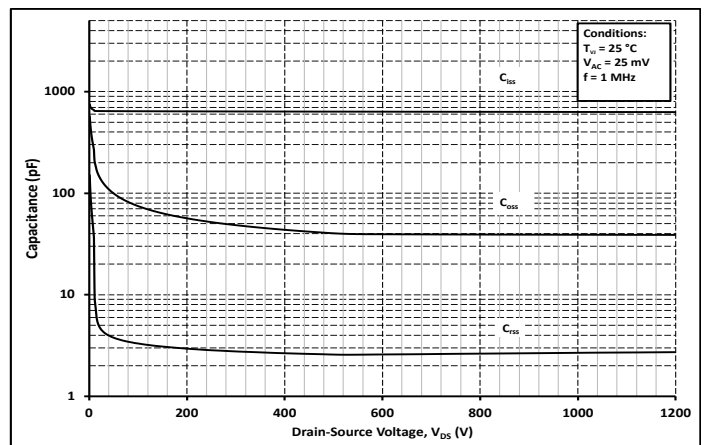
**Figure 16.**

Output Capacitor Stored Energy



**Figure 17.**

Capacitances vs. Drain-Source Voltage (0-200V)

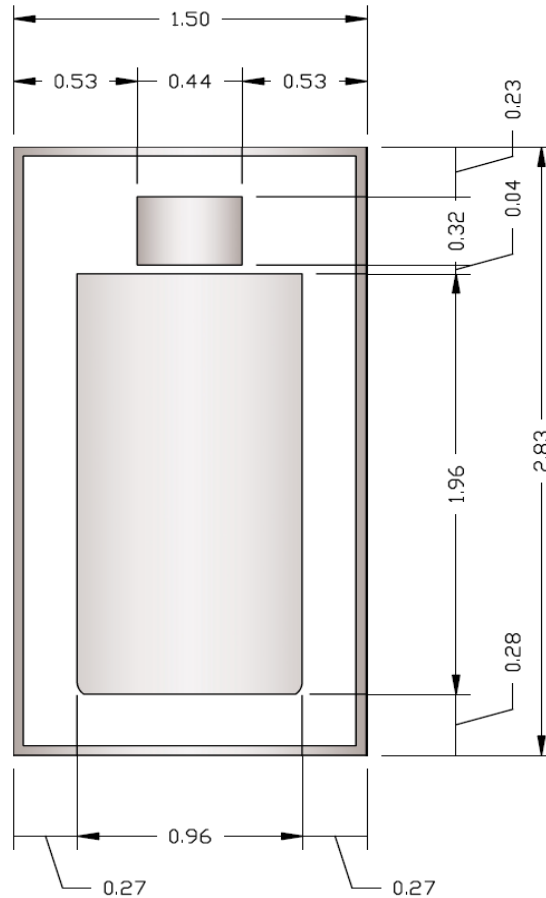


**Figure 18.**

Capacitances vs. Drain-Source Voltage (0-650V)



## Product Dimensions CPM3-1200-0160A



## Product Dimensions CPM3-1200-0160A

Parameter	Typical	Units
Die Size (L x W)	1.50 x 2.83	mm
Exposed Source Pad Metal Dimensions	1.96 x 0.96 (x1)	mm
Gate Pad Dimensions	0.44 x 0.32	mm
Chip Thickness <sup>1</sup>	180 ± 20	µm
Frontside (Source) metalization (Al)	4	µm
Frontside (Gate) metalization (Al)	4	µm
Backside (Drain) metalization (Ni:Au)	0.8 / 0.1	µm

<sup>1</sup>SiC wafer thickness



## Product Ordering Information

Order Number	Description	Package
CPM3-1200-0160A-FY6	1200V/160mΩ SiC MOSFET G3 IND UV MUL	Bare Die Product

## Revision History

Revision History	Date of Change	Brief Summary
1	07/27/2022	Initial Release.



## Notes & Disclaimer

---

This document and the information contained herein are subject to change without notice. Any such change shall be evidenced by the publication of an updated version of this document by Wolfspeed. No communication from any employee or agent of Wolfspeed or any third party shall effect an amendment or modification of this document. No responsibility is assumed by Wolfspeed for any infringement of patents or other rights of third parties which may result from use of the information contained herein. No license is granted by implication or otherwise under any patent or patent rights of Wolfspeed.

Notwithstanding any application-specific information, guidance, assistance, or support that Wolfspeed may provide, the buyer of this product is solely responsible for determining the suitability of this product for the buyer's purposes, including without limitation for use in the applications identified in the next bullet point, and for the compliance of the buyers' products, including those that incorporate this product, with all applicable legal, regulatory, and safety-related requirements.

This product has not been designed or tested for use in, and is not intended for use in, applications in which failure of the product would reasonably be expected to cause death, personal injury, or property damage, including but not limited to equipment implanted into the human body, life-support machines, cardiac defibrillators, and similar emergency medical equipment, aircraft navigation, communication, and control systems, aircraft power and propulsion systems, air traffic control systems, and equipment used in the planning, construction, maintenance, or operation of nuclear facilities.

### **RoHS Compliance**

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Wolfspeed representative or from the Product Documentation sections of [www.wolfspeed.com](http://www.wolfspeed.com).

### **REACH Compliance**

REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact your Wolfspeed representative to ensure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

### **Contact info:**

4600 Silicon Drive  
Durham, NC 27703 USA  
Tel: +1.919.313.5300  
[www.wolfspeed.com/power](http://www.wolfspeed.com/power)